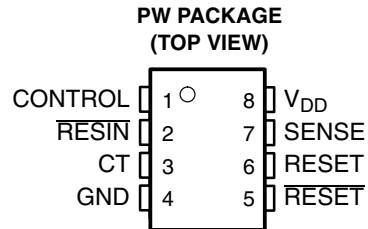


TLC7701-Q1, TLC7705-Q1, TLC7733-Q1 MICROPOWER SUPPLY VOLTAGE SUPERVISORS

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- Qualified for Automotive Applications
- Power-On Reset Generator
- Automatic Reset Generation After Voltage Drop
- Precision Voltage Sensor
- Temperature-Compensated Voltage Reference
- Programmable Delay Time by External Capacitor
- Supply Voltage Range . . . 2 V to 6 V
- Defined $\overline{\text{RESET}}$ Output from $V_{\text{DD}} \geq 1 \text{ V}$
- Power-Down Control Support for Static RAM With Battery Backup
- Maximum Supply Current of 16 μA
- Power Saving Totem-Pole Outputs



description

The TLC77xx family of micropower supply voltage supervisors provide reset control, primarily in microcomputer and microprocessor systems.

During power-on, $\overline{\text{RESET}}$ is asserted when V_{DD} reaches 1 V. After minimum $V_{\text{DD}} (\geq 2 \text{ V})$ is established, the circuit monitors SENSE voltage and keeps the reset outputs active as long as SENSE voltage ($V_{\text{I(SENSE)}}$) remains below the threshold voltage. An internal timer delays return of the output to the inactive state to ensure proper system reset. The delay time, t_{d} , is determined by an external capacitor:

$$t_{\text{d}} = 2.1 \times 10^4 \times C_{\text{T}}$$

Where

C_{T} is in farads

t_{d} is in seconds

Except for the TLC7701, which can be customized with two external resistors, each supervisor has a fixed SENSE threshold voltage set by an internal voltage divider. When SENSE voltage drops below the threshold voltage, the outputs become active and stay in that state until SENSE voltage returns above threshold voltage and the delay time, t_{d} , has expired.

In addition to the power-on-reset and undervoltage-supervisor function, the TLC77xx adds power-down control support for static RAM. When CONTROL is tied to GND, RESET will act as active high. The voltage monitor contains additional logic intended for control of static memories with battery backup during power failure. By driving the chip select ($\overline{\text{CS}}$) of the memory circuit with the RESET output of the TLC77xx and with the CONTROL driven by the memory bank select signal ($\overline{\text{CSH1}}$) of the microprocessor (see Figure 10), the memory circuit is automatically disabled during a power loss. (In this application the TLC77xx power has to be supplied by the battery.)



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

 **TEXAS
INSTRUMENTS**

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TLC7701-Q1, TLC7705-Q1, TLC7733-Q1 MICROPOWER SUPPLY VOLTAGE SUPERVISORS

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ORDERING INFORMATION†‡

T _A	PACKAGE§		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 125°C	TSSOP – PW	Tape and reel	TLC7701QPWRQ1	7701Q1
	TSSOP – PW	Tape and reel	TLC7705QPWRQ1	7705Q1
	TSSOP – PW	Tape and reel	TLC7733QPWRQ1	7733Q1

† For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at <http://www.ti.com>.

‡ Package drawings, thermal data, and symbolization are available at <http://www.ti.com/packaging>.

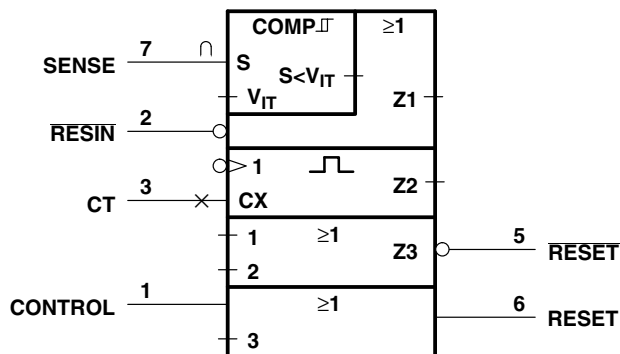
§ The PW package is only available left-end taped and reeled (indicated by the R suffix on the device type; e.g., TLC7701QPWRQ1).

FUNCTION TABLE

CONTROL	RESIN	V _{I(SENSE)} > V _{IT+}	RESET	RESET
L	L	False	H	L
L	L	True	H	L
L	H	False	H	L
L	H	True	L§	H§
H	L	False	H	L
H	L	True	H	L
H	H	False	H	L
H	H	True	H	H§

§ RESET and RESET states shown are valid for t > t_d.

logic symbol¶

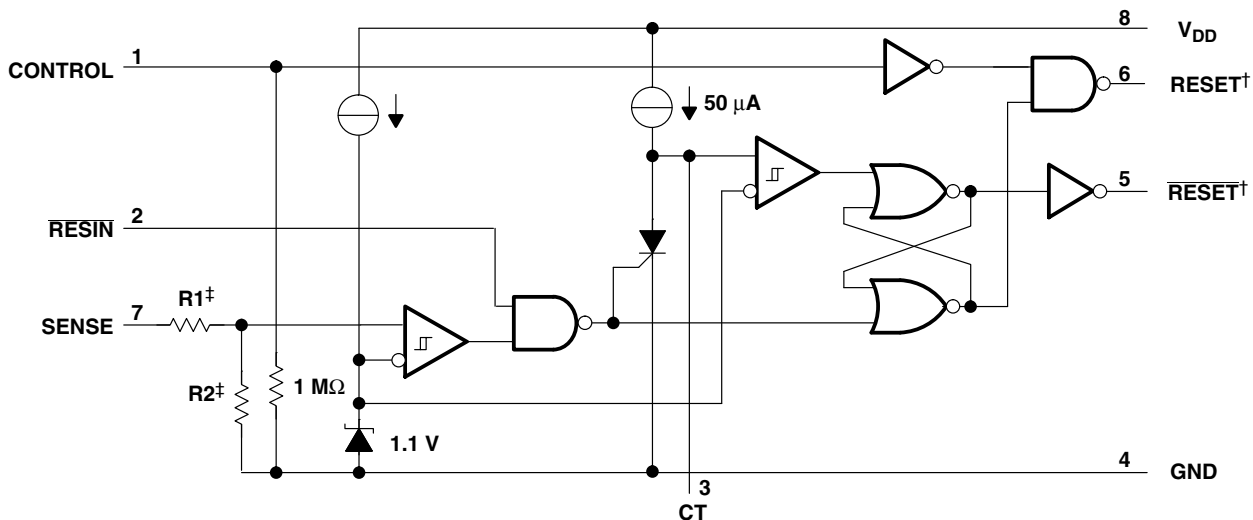


¶ This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

TLC7701-Q1, TLC7705-Q1, TLC7733-Q1 MICROPOWER SUPPLY VOLTAGE SUPERVISORS

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functional block diagram



† Outputs are totem-pole configuration. External pullup or pulldown resistors are not required.

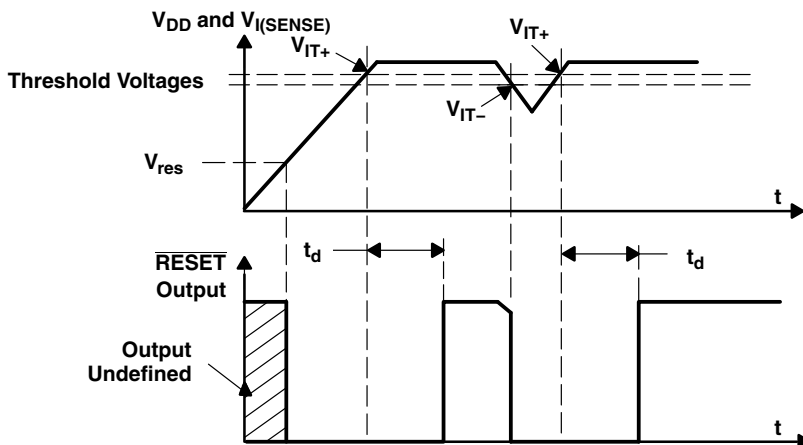
‡ Nominal values:

	R1 (Typ)	R2 (Typ)
TLC7701	0	∞
TLC7705	910 k Ω	290 k Ω
TLC7733	750 k Ω	450 k Ω

TLC7701-Q1, TLC7705-Q1, TLC7733-Q1 MICROPOWER SUPPLY VOLTAGE SUPERVISORS

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timing diagram



absolute maximum ratings over operating free-air temperature (unless otherwise noted)[†]

Supply voltage, V_{DD} (see Note 1)	7 V
Input voltage range, CONTROL, $\overline{\text{RESIN}}$, SENSE (see Note 1)	-0.3 V to 7 V
Maximum low output current, I_{OL}	10 mA
Maximum high output current, I_{OH}	-10 mA
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{DD}$)	± 10 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{DD}$)	± 10 mA
Continuous total power dissipation	See Dissipation Rating Table
Operating free-air temperature range, T_A : TL77xxQ	-40°C to 125°C
Storage temperature range, T_{stg}	-65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values are with respect to GND.

DISSIPATION RATING TABLE

PACKAGE	$T_A \leq 25^\circ\text{C}$ POWER RATING	DERATING FACTOR ABOVE $T_A = 25^\circ\text{C}$	$T_A = 85^\circ\text{C}$ POWER RATING	$T_A = 125^\circ\text{C}$ POWER RATING
PW	525 mW	4.2 mW/°C	273 mW	105 mW

recommended operating conditions at specified temperature range

	MIN	MAX	UNIT
Supply voltage, V_{DD}	2	6	V
Input voltage, V_I	0	V_{DD}	V
High-level input voltage at $\overline{\text{RESIN}}$ and CONTROL [‡] , V_{IH}	$0.7 \times V_{DD}$		V
Low-level input voltage at $\overline{\text{RESIN}}$ and CONTROL [‡] , V_{IL}		$0.2 \times V_{DD}$	V
High-level output current, I_{OH}		-2	mA
Low-level output current, I_{OL}	$V_{DD} \geq 2.7$ V	2	mA
Input transition rise and fall rate at $\overline{\text{RESIN}}$ and CONTROL, $\Delta t/\Delta V$		100	ns/V
Operating free-air temperature range, T_A	-40	125	°C

[‡] To ensure a low supply current, V_{IL} should be kept < 0.3 V and $V_{IH} > V_{DD} - 0.3$ V.



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TLC7701-Q1, TLC7705-Q1, TLC7733-Q1 MICROPOWER SUPPLY VOLTAGE SUPERVISORS

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electrical characteristics over recommended operating conditions (see Note 2) (unless otherwise noted)

PARAMETER		TEST CONDITIONS	TLC77xx			UNIT	
			MIN	TYP†	MAX		
V _{OH}	High-level output voltage	I _{OH} = -20 μA	V _{DD} = 2 V	1.8		V	
			V _{DD} = 2.7 V	2.5			
			V _{DD} = 4.5 V	4.3			
		I _{OH} = -2 mA	V _{DD} = 4.5 V	3.7			
V _{OL}	Low-level output voltage	I _{OL} = 20 μA	V _{DD} = 2 V	0.2		V	
			V _{DD} = 2.7 V	0.2			
			V _{DD} = 4.5 V	0.2			
		I _{OL} = 2 mA	V _{DD} = 4.5 V	0.5			
V _{IT-}	Negative-going input threshold voltage, SENSE (see Note 3)	TLC7701	V _{DD} = 2 V to 6 V	1.04	1.1	1.16	V
		TLC7705		4.43	4.5	4.63	
		TLC7733		2.855	2.93	3.03	
V _{hys}	Hysteresis voltage, SENSE	TLC7701	V _{DD} = 2 V to 6 V	30		mV	
		TLC7705		70			
		TLC7733					
V _{res}	Power-up reset voltage‡	I _{OL} = 20 μA			1	V	
I _I	Input current	RESIN	V _I = 0 V to V _{DD}			2	μA
		CONTROL	V _I = V _{DD}		7	15	
		SENSE	V _I = 5 V		5	10	
		SENSE, TLC7701 only	V _I = 5 V			2	
I _{DD}	Supply current	RESIN = V _{DD} , SENSE = V _{DD} ≥ V _{ITmax} + 0.2 V CONTROL = 0 V, Outputs open		9	16	μA	
I _{DD(d)}	Supply current during t _d	V _{DD} = 5 V, V _{CT} = 0, RESIN = V _{DD} , SENSE = V _{DD} , CONTROL = 0 V, Outputs open		120	150	μA	
C _I	Input capacitance, SENSE	V _I = 0 V to V _{DD}		50		pF	

† Typical values apply at T_A = 25°C.

‡ The lowest supply voltage at which RESET becomes active. The symbol V_{res} is not currently listed within EIA or JEDEC standards for semiconductor symbology. Rise time of V_{DD} ≥ 15 μs/V.

NOTES: 2. All characteristics are measured with C_T = 0.1 μF.

3. To ensure best stability of the threshold voltage, a bypass capacitor (ceramic, 0.1 μF) should be connected near the supply terminals.



TLC7701-Q1, TLC7705-Q1, TLC7733-Q1 MICROPOWER SUPPLY VOLTAGE SUPERVISORS

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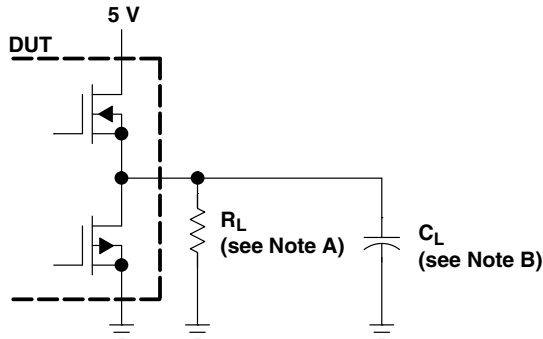
switching characteristics at $V_{DD} = 5\text{ V}$, $R_L = 2\text{ k}\Omega$, $C_L = 50\text{ pF}$, $T_A = \text{Full Range}$ (unless otherwise noted)

PARAMETER	MEASURED		TEST CONDITIONS	TLC77xx			UNIT
	FROM (INPUT)	TO (OUTPUT)		MIN	TYP	MAX	
t_d Delay time	$V_{I(\text{SENSE})} \geq V_{IT+}$	RESET and RESET	$\overline{\text{RESIN}} = 0.7 \times V_{DD}$, $\text{CONTROL} = 0.2 \times V_{DD}$, $C_T = 100\text{ nF}$, $T_A = \text{Full range}$, See timing diagram	1.1	2.1	4.2	ms
t_{PLH} Propagation delay time, low-to-high-level output	SENSE	RESET	$V_{IH} = V_{IT+max} + 0.2\text{ V}$, $V_{IL} = V_{IT-min} - 0.2\text{ V}$, $\overline{\text{RESIN}} = 0.7 \times V_{DD}$, $\text{CONTROL} = 0.2 \times V_{DD}$, $CT = \text{NC}^\dagger$	20			μs
t_{PHL} Propagation delay time, high-to-low-level output				5			
t_{PLH} Propagation delay time, low-to-high-level output		5					
t_{PHL} Propagation delay time, high-to-low-level output		20					
t_{PLH} Propagation delay time, low-to-high-level output	$\overline{\text{RESIN}}$	RESET	$V_{IH} = 0.7 \times V_{DD}$, $V_{IL} = 0.2 \times V_{DD}$, $\text{SENSE} = V_{IT+max} + 0.2\text{ V}$, $\text{CONTROL} = 0.2 \times V_{DD}$, $CT = \text{NC}^\dagger$	20			μs
t_{PHL} Propagation delay time, high-to-low-level output				60			
t_{PLH} Propagation delay time, low-to-high-level output		65			ns		
t_{PHL} Propagation delay time, high-to-low-level output		20					
t_{PLH} Propagation delay time, low-to-high-level output	CONTROL	RESET	$V_{IH} = 0.7 \times V_{DD}$, $V_{IL} = 0.2 \times V_{DD}$, $\text{SENSE} = V_{IT+max} + 0.2\text{ V}$, $\overline{\text{RESIN}} = 0.7 \times V_{DD}$, $CT = \text{NC}^\dagger$	58			ns
t_{PHL} Propagation delay time, high-to-low-level output				58			
Low-level minimum pulse duration to switch RESET and RESET	SENSE		$V_{IH} = V_{IT+max} + 0.2\text{ V}$, $V_{IL} = V_{IT-min} - 0.2\text{ V}$, $V_{IL} = 0.2 \times V_{DD}$, $V_{IH} = 0.7 \times V_{DD}$	3			μs
	$\overline{\text{RESIN}}$			1			
t_r Rise time		RESET and RESET	10% to 90%	8			ns/V
t_f Fall time			90% to 10%	4			

† NC = No capacitor, and includes up to 100-pF probe and jig capacitance.



PARAMETER MEASUREMENT INFORMATION



NOTES: A. For switching characteristics, $R_L = 2\text{ k}\Omega$.
B. $C_L = 50\text{ pF}$ includes jig and probe capacitance.

Figure 1. RESET AND $\overline{\text{RESET}}$ Output Configurations

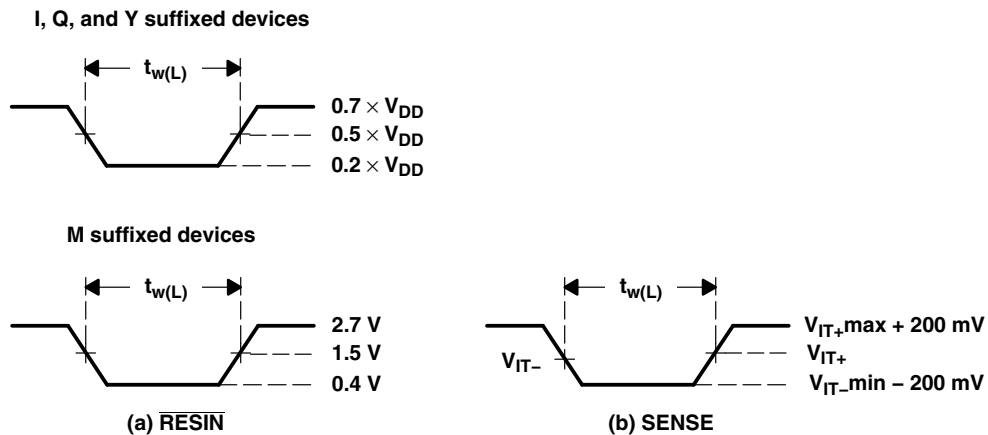


Figure 2. Input Pulse Definition Waveforms

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TYPICAL CHARACTERISTICS

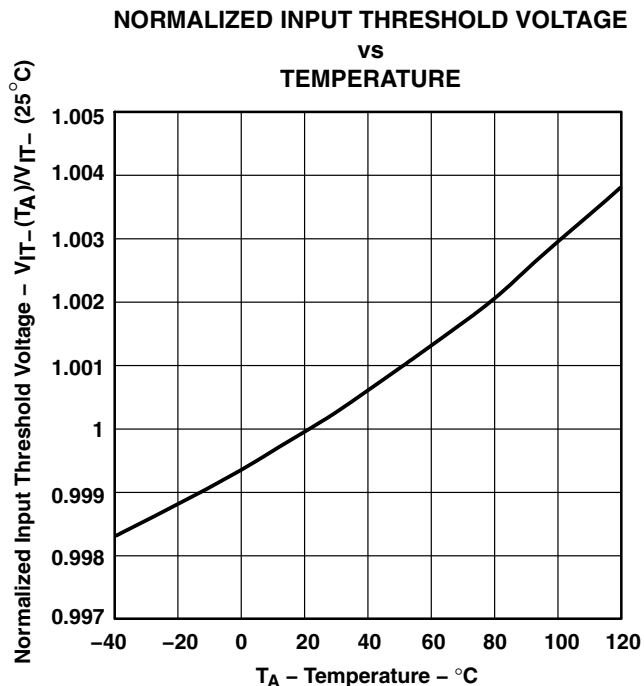


Figure 3

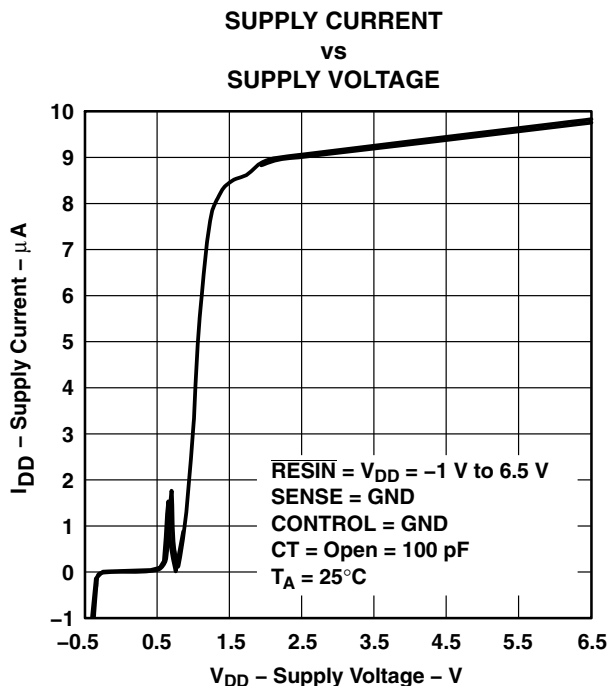


Figure 4

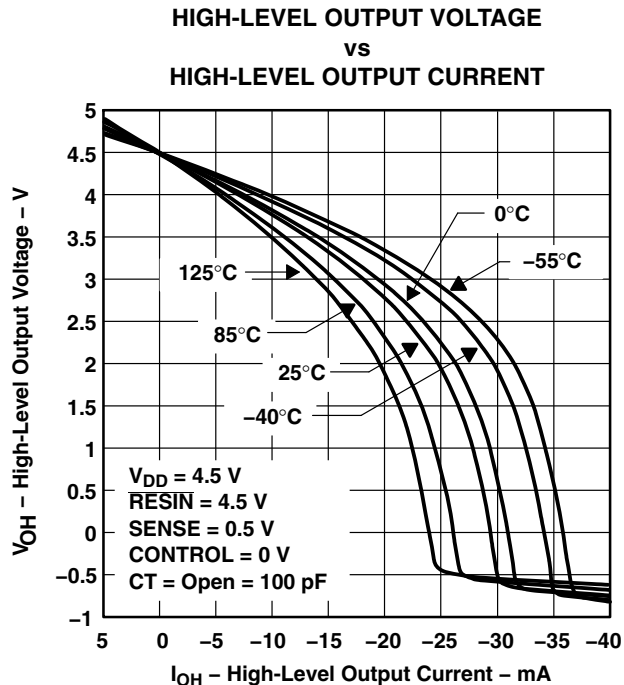


Figure 5

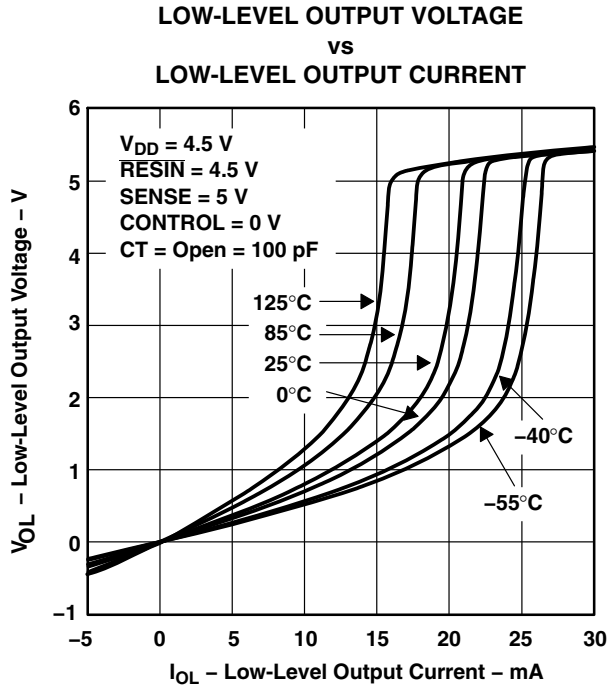
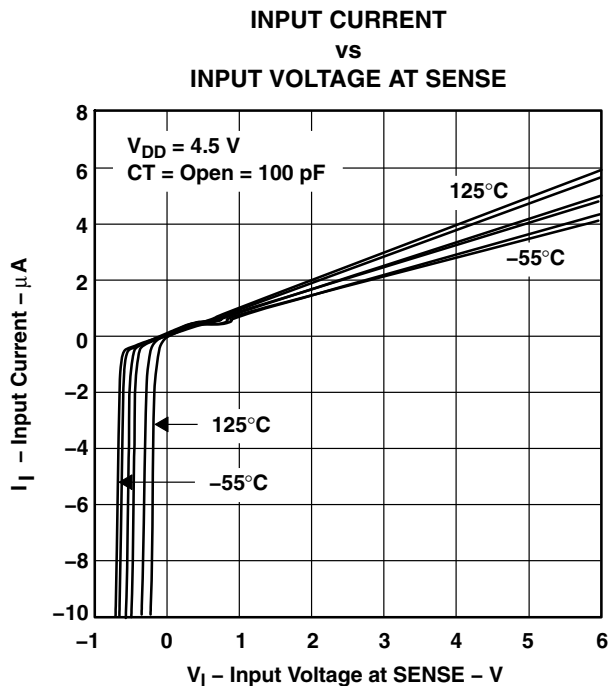


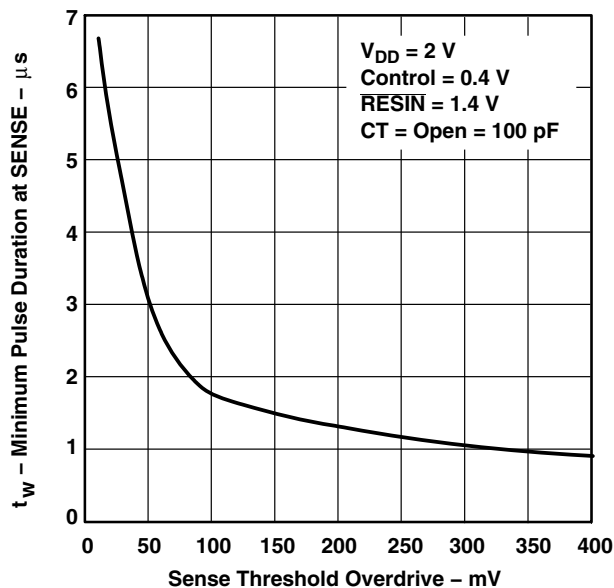
Figure 6



TYPICAL CHARACTERISTICS



**MINIMUM PULSE DURATION AT SENSE
vs
SENSE THRESHOLD OVERDRIVE**



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APPLICATION INFORMATION

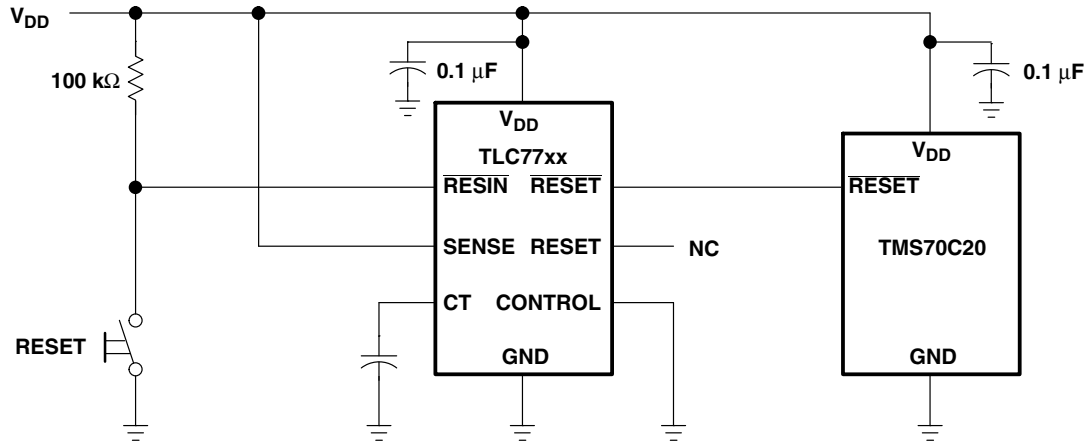


Figure 9. Reset Controller in a Microcomputer System

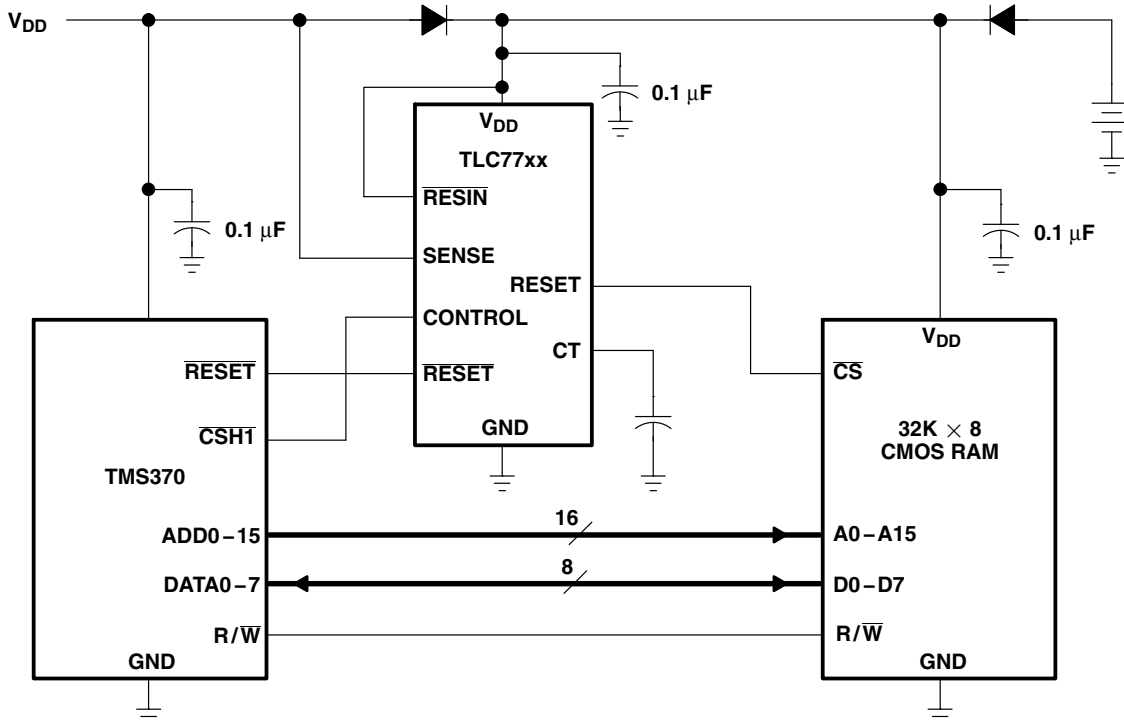


Figure 10. Data Retention During Power Down Using Static CMOS RAMs

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Samples (Requires Login)
TLC7701QPWRG4Q1	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TLC7701QPWRQ1	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TLC7705QPWRG4Q1	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TLC7705QPWRQ1	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TLC7733QPWRG4Q1	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TLC7733QPWRQ1	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF TLC7701-Q1, TLC7705-Q1, TLC7733-Q1 :

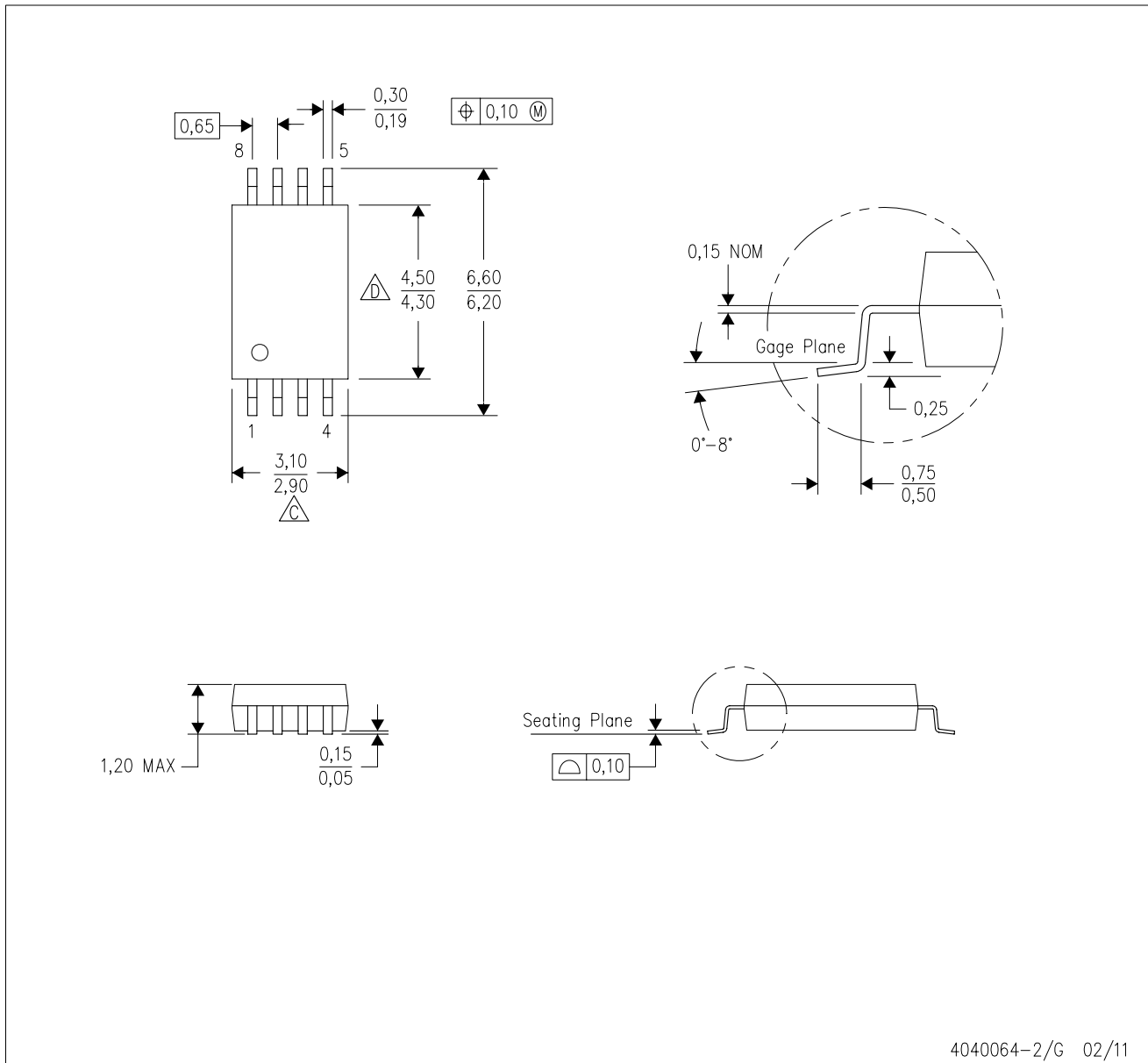
- Catalog: [TLC7701](#), [TLC7705](#), [TLC7733](#)
- Enhanced Product: [TLC7701-EP](#), [TLC7705-EP](#), [TLC7733-EP](#)
- Military: [TLC7705M](#), [TLC7733M](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Enhanced Product - Supports Defense, Aerospace and Medical Applications
- Military - QML certified for Military and Defense Applications

PW (R-PDSO-G8)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
 - E. Falls within JEDEC MO-153

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